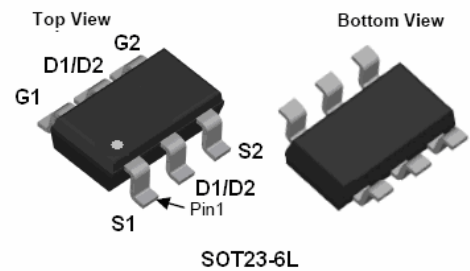
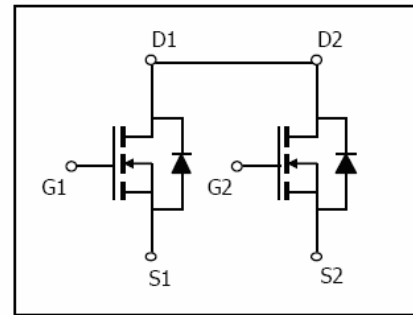


Features

- ◆ Ron(typ.)=22 mΩ @VGS=4.5V
- ◆ Low On-Resistance
- ◆ 150°C Operating Temperature
- ◆ Fast Switching
- ◆ Lead-Free, RoHS Compliant

Description

VS8205AS designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective . These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.


Absolute Maximum Ratings

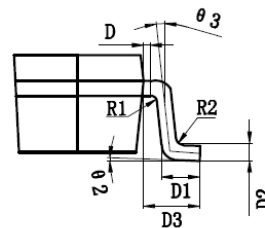
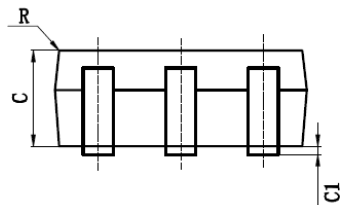
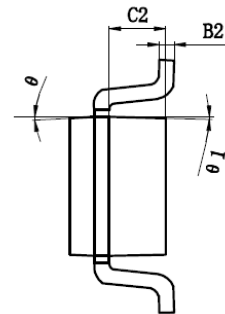
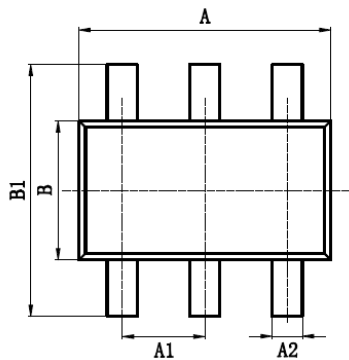
Symbol	Parameter		Rating	Unit
Common Ratings (T_c=25°C Unless Otherwise Noted)				
V _{GS}	Gate-Source Voltage		±12	V
V _{(BR)DSS}	Drain-Source Breakdown Voltage		20	V
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-50 to 155	°C
I _S	Diode Continuous Forward Current	T _c =25°C	6 ^①	A
Mounted on Large Heat Sink				
I _{DM}	Pulse Drain Current Tested	T _c =25°C	22	A
I _D	Continuous Drain Current(VGS=10V)	T _c =25°C	6 ^①	A
		T _c =100°C	4.0	
P _D	Maximum Power Dissipation	T _c =25°C	1.45	W
R _{θJA}	Thermal Resistance Junction-Ambient		99	°C/W

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current (T _c =25°C)	V _{DS} =20V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current (T _c =125°C)	V _{DS} =20V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.4	0.7	1.2	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =4.5A	--	20	25	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} 2.5V, I _D =3.5A	--	30	40	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1MHz	--	610	--	pF
C _{oss}	Output Capacitance		--	320	--	pF
C _{rss}	Reverse Transfer Capacitance		--	145	--	pF
Q _g	Total Gate Charge	V _{DS} =10V, I _D =1A, V _{GS} =4.5V	--	11	--	nC
Q _{gs}	Gate-Source Charge		--	2.2	--	nC
Q _{gd}	Gate-Drain Charge		--	1.5	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =10V, I _D =1A, R _G =6Ω, V _{GS} =4.5V, R _L =5Ω,	--	10	--	nS
t _r	Turn-on Rise Time		--	11	--	nS
t _{d(off)}	Turn-Off Delay Time		--	35	--	nS
t _f	Turn-Off Fall Time		--	31	--	nS
Source- Drain Diode Characteristics						
I _{SD}	Source-drain current(Body Diode)	T _c =25°C	--	--	5.6 ^①	A
I _{SDM}	Pulsed Source-drain current (Body Diode)		--	--	16 ^①	A
V _{SD}	Forward on voltage	T _J =25°C, I _{SD} =2.8A, V _{GS} =0V	--	0.85	1.3	V

Notes: ① Pulse test ; Pulse width≤300μs, duty cycle≤2%.

SOT23-6L Mechanical Data

REF.	Size	Min.(mm)	Max.(mm)	REF.	Size	Min.(mm)	Max.(mm)
A		2.82	3.02	D1		0.40	0.50
A1		0.90	1.00	D2		0.254TYP	
A2		0.35	0.45	D3		0.60	0.70
B		1.52	1.72	θ		9° TYP4	
B1		2.80	3.00	θ 1		10° TYP4	
B2		0.119	0.135	θ 2		0° ~ 8°	
C		1.05	1.15	θ 3		6° TYP	
C1		0.03	0.13	R		<0.2TYP4	
C2		0.60	0.70	R1		0.08TYP	
D		0.03	0.13	R2		0.08TYP	



Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS8205AS	8205A	SOT23-6L	3000/Reel	6000

Customer Service

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